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General Information

Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
Typical Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	1.25mm +/-0.15mm
S	0.7mm MIN
B	0.5mm +/-0.25mm
Case Code (EIA / mm)	0805 / 2012

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Dimensions

Capacitance	240 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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